



Material Content Data Sheet



| Sales Product Name | | BSS306N H6327 | | Issued | | 29. August 2013 | | |
|---------------------------|--------------------|----------------|--------------------|----------------|------------------|-----------------|--------------------|-----------|
| MA# | | MA000933192 | | | | | | |
| Package | | PG-SOT23-3-5 | | Weight* | | 9.42 mg | | |
| Construction Element | Material Group | Substances | CAS# if applicable | Weight [mg] | Average Mass [%] | Sum [%] | Average Mass [ppm] | Sum [ppm] |
| chip | non noble metal | tin | 7440-31-5 | 0.004 | 0.05 | | 468 | |
| | noble metal | gold | 7440-57-5 | 0.017 | 0.18 | | 1816 | |
| | inorganic material | silicon | 7440-21-3 | 0.261 | 2.77 | 3.00 | 27707 | 29991 |
| leadframe | non noble metal | chromium | 7440-47-3 | 0.009 | 0.10 | | 960 | |
| | inorganic material | silicon | 7440-21-3 | 0.001 | 0.01 | | 64 | |
| | non noble metal | titanium | 7440-32-6 | 0.003 | 0.03 | | 320 | |
| | non noble metal | copper | 7440-50-8 | 3.000 | 31.86 | 32.00 | 318553 | 319897 |
| wire | non noble metal | copper | 7440-50-8 | 0.073 | 0.77 | 0.77 | 7722 | 7722 |
| encapsulation | organic material | carbon black | 1333-86-4 | 0.056 | 0.60 | | 5963 | |
| | plastics | epoxy resin | - | 1.208 | 12.82 | | 128206 | |
| | inorganic material | silicondioxide | 60676-86-0 | 4.353 | 46.20 | 59.62 | 462137 | 596306 |
| leadfinish | non noble metal | tin | 7440-31-5 | 0.150 | 1.59 | 1.59 | 15887 | 15887 |
| plating | noble metal | silver | 7440-22-4 | 0.284 | 3.02 | 3.02 | 30197 | 30197 |
| *deviation | < 10% | | | Sum in total: | | 100.00 | | 1000000 |

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

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